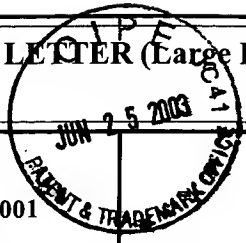


1765

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Naokatsu Ikegami		Docket No. OKI.286	
Serial No. 09/996,788	Filing Date November 30, 2001	Examiner K. Chen	Group Art Unit 1765



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Invention: **METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE**

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.
The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	1 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **50-0238**
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☒ Any patent application processing fees under 37 CFR 1.17.

Signature

Dated: **June 25, 2003**

ANDREW J. TELESZ, JR.
REG. NO. 33,581

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I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
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Typed or Printed Name of Person Mailing Correspondence

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7/2/03
OKI.286

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Naokatsu Ikegami

Group Art Unit: 1765

Serial No.: 09/996,788

Examiner: K. Chen

Filed: November 30, 2001

For: METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Date: June 25, 2003

Sir:

In response to the Office Action dated April 7, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

In the Abstract:

Please cancel the Abstract and replace with the Abstract attached herewith.

In the Specification:

Replace the paragraph beginning on page 7, line 16 with the following paragraph:

"In the example shown in Fig. 1(a), in the insulating layer 23, a second

A1 conductive member 25 is embedded as a lower electrode member below the electrode